

Solder Paste for Laser application

In order to reduce overheating issues against components, working time reduction, fine spot soldering as well as less populated PCB, non contacting solder is preferred.

SSI-M

Halogen flux solder paste for LASER

NH-LS

Non Halogen solder paste for LASER



Feature

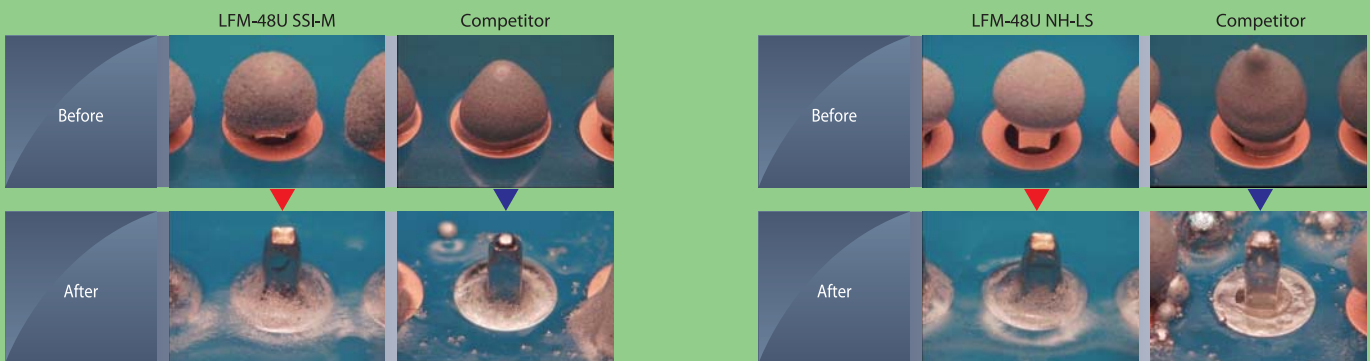
- Best for non contact soldering of various kind (laser, hologen lamp etc)
- Stable dispensing characteristic allows control of solder amount simple.
- Low splattering under quick heating condition.
- Easy to fit best working condition.

Evaluation

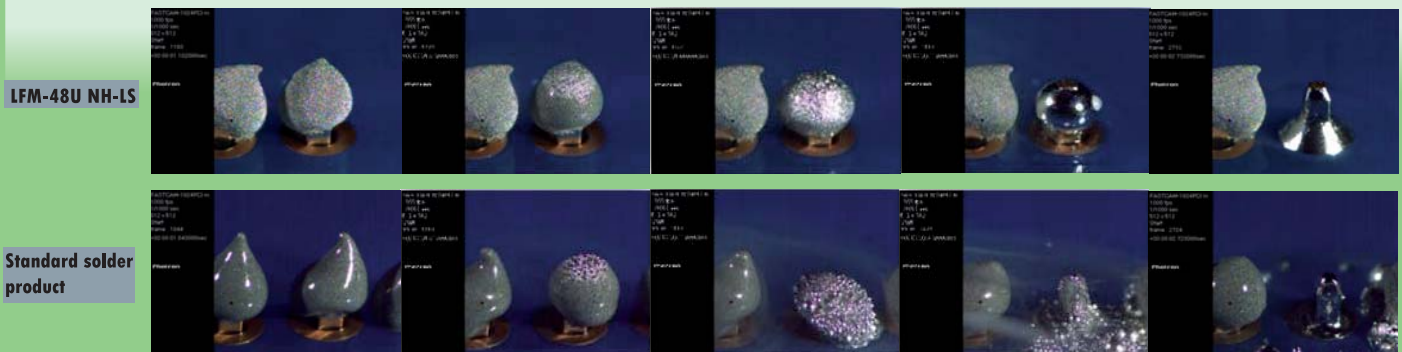
Wettability Validation

Diode Laser
Output 0-30W 1.5 sec

Connector \varnothing 1.0mm thru-hole



Laser wetting property (High speed camera)



Product name components for solder paste

(Example) LFM-48 U NH-LS 13%

Alloy name; Powder size; Flux name; Flux content

Solder Paste Specification

Flux Name	Alloy Name	Alloy Composition	Powder Name: Size	Flux Content	Viscosity
NH-LS	LFM-48	Sn-3.0Ag-0.5Cu	X: 25-45 μ m	13.0wt%	80Pa·s
			W: 20-38 μ m		
			U: 10-28 μ m		
SSI-M	LFM-48	Sn-3.0Ag-0.5Cu	X: 25-45 μ m	13.0wt%	80Pa·s
			W: 20-38 μ m		
			U: 10-28 μ m		

※LFM-48 is sublicense product of US PAT No. 5527628.